

ABSTRACT OF THE DISCLOSURE

In a method of fabricating a multi-layer circuit board assembly, at least two multi-layer circuit board modules are provided. Each of the modules has a lateral edge provided with a plurality of solder pads that are connected electrically with module interconnect circuit traces on a respective one of the modules. The modules are stacked one upon the other, and are bonded together such that the solder pads of one of the modules are connected to registered ones of the solder pads of the other one of the modules, thereby establishing electrical connection among the circuit traces on the modules.

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